



Product data sheet SP48G panel express

Backing	G-paper														
Bonding	Synthetic resin														
Grain	Silicon carbide														
Coating	Dense														
Application area	Wood (chipboards, MDF boards, HDF boards, OSB boards, HPL boards)														
Application	Wide-belt, long-belt and edged-belt grinding machines														
Advantages	The combination of silicon carbide grains, special binding and an extra heavy G-paper backing guarantee high abrasive power as well as a fine grinding finish, long lifetime and smooth belt running.														
Recommendation	HDF	MDF	OSB	Cement fibre	Chipboard	Plywood	Solid wood	HPL							
Calibration grind			● ☆					● ☆							
Intermediate grind			● ☆					● ☆							
Final Grind	•		● ☆			● ☆		● ☆							
Roughening	ning														



- Higher and faster chip removal power
- Excellent for fine grinding with high demands
- ★ Exceptional cases

o removal power ding with high demands

Available grits

						Cont																			
16	20	24	30	36	40	50	60	80	100	120	150	180	220	240	280	320	360	400	500	600	800	900	1000	1200	1500

Application



Stationary machine sanding

Product range









Segment bel

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